

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

1. (Currently Amended) A method for manufacturing a circuit board comprising:

attaching a mask film to a substrate in at least one squeegee area, the mask film including a first surface opposite a surface attached to the substrate;

forming a plurality of depressions in the first surface in the at least one squeegee area, each depression defining a perimeter portion, each perimeter portion surrounded by a respective periphery having an elevation higher than an elevation of the first surface;

forming a through-hole through the mask film and the substrate in the at least one squeegee area; filling conductive paste into the through-hole by using a squeezing operation in the at least one squeegee area; and

cleaning a squeegee using the formed plurality of depressions during the squeezing operation.

2. (Currently Amended) A method for manufacturing a circuit board comprising:

attaching a mask film to a substrate in at least one squeegee area, the mask film including a first surface opposite a surface attached to the substrate;

forming a squeegee cleaning part at the first surface in the at least one squeegee area, the squeegee cleaning part defining a perimeter portion having a plurality of depressions in the first surface, each depression surrounded by a respective periphery having an elevation higher than an elevation of the first surface;

forming a through-hole through the substrate and the mask film in the at least one squeegee area;

filling conductive paste into the through-hole by using a squeezing operation in the at least one squeegee area; and

cleaning a squeegee using the squeegee cleaning part during the squeezing operation,

wherein the squeegee cleaning part is formed at a predetermined position in the mask film before the filling of the conductive paste.

3. (Previously Presented) The method for manufacturing a circuit board of claim 1,

wherein the plurality of depressions are formed at a position which is not used to form a portion of the circuit board or an area outside of a product area of a paste-filling area of the mask film and within a printing range.

4. (Previously Presented) The method for manufacturing a circuit board of claim 1,

wherein each depression is a through-hole formed in the mask film.

5. (Previously Presented) The method for manufacturing a circuit board of claim 1,

wherein each depression is a linear groove formed at a paste-filling area of the mask film, the linear groove being formed so as not to penetrate through the substrate.

6. - 7. (Cancelled)

8. (Previously Presented) The method for manufacturing a circuit board of claim 5,

wherein the forming of each linear groove of the mask film includes processing the linear groove using a cutting edge.

9. (Original) The method for manufacturing a circuit board of claim 8,

wherein the cutting edge is a round blade.

10. (Original) The method for manufacturing a circuit board of claim 9,

wherein the round blade is fixed to a blade-fixing section having vertically sliding function with a certain load so as not to rotate.

11. (Previously Presented) The method for manufacturing a circuit board of claim 10, further comprising setting a depth of the linear groove and the elevation of the perimeter portion of the plurality of depressions by adjusting an edge angle of the round blade and a load.

12. (Previously Presented) The method for manufacturing a circuit board of claim 1,

wherein the elevation of the perimeter portion of each depression is above the first surface by 3 μ m or more.

13. (Previously Presented) The method for manufacturing a circuit board of claim 1,

wherein the substrate is a prepreg where resin material, whose main body is thermosetting resin, is impregnated into a fabric or a nonwoven fabric, thereby forming B-stage.

14. (Previously Presented) The method for manufacturing a circuit board of claim 13,

wherein aramid fabric is the main body of the fabric or the nonwoven fabric.

15. (Previously Presented) The method for manufacturing a circuit board of claim 13,

wherein glass fiber is the main body of the fabric or the nonwoven fabric.

16. (Previously Presented) The method for manufacturing a circuit board of claim 1, wherein:

the filling of the conductive paste into the through-hole by using the squeezing operation comprises:

filling the conductive paste into the through-hole by reciprocating the squeegee on the circuit board; and

the cleaning of the squeegee using the formed plurality of depressions during the squeezing operation includes cleaning an edge of the squeegee by using the plurality of depressions.

17. - 22. (Cancelled)

23. (Previously Presented) The method for manufacturing a circuit board of claim 2,

wherein the predetermined position is a position which is not used to form a portion of the circuit board or an area outside of a product area of a paste-filling area of the mask film and within a printing range.

24. (Previously Presented) The method for manufacturing a circuit board of claim 2,

wherein the squeegee cleaning part is a linear groove formed at a paste-filling area of the mask film, the linear groove being formed so as not to penetrate through the substrate.

25. (Previously Presented) The method for manufacturing a circuit board of claim 24,

wherein the squeegee cleaning part is a plurality of the linear grooves.

26. (Cancelled)

27. (Previously Presented) The method for manufacturing a circuit board of claim 24,

wherein the forming of the linear groove of the mask film includes processing the linear groove using a cutting edge.

28. (Previously Presented) The method for manufacturing a circuit board of claim 27,

wherein the cutting edge is a round blade.

29. (Previously Presented) The method for manufacturing a circuit board of claim 28,

wherein the round blade is fixed to a blade-fixing section having vertically sliding function with a certain load so as not to rotate.

30. (Previously Presented) The method for manufacturing a circuit board of claim 29, further comprising setting a depth of the linear groove and the elevation of the perimeter portion of the squeegee cleaning part by adjusting an edge angle of the round blade and the load.

31. (Previously Presented) The method for manufacturing a circuit board of claim 2,

wherein the elevation of the perimeter portion is above the first surface by $3\mu\text{m}$ or more.

32. (Previously Presented) The method for manufacturing a circuit board of claim 2,

wherein the substrate is a prepreg where resin material, whose main body is thermosetting resin, is impregnated into a fabric or a nonwoven fabric, thereby forming B-stage.

33. (Previously Presented) The method for manufacturing a circuit board of claim 32,

wherein aramid fabric is the main body of the fabric or the nonwoven fabric.

34. (Previously Presented) The method for manufacturing a circuit board of claim 32,

wherein glass fiber is the main body of the fabric or the nonwoven fabric.

35. (Previously Presented) The method for manufacturing a circuit board of claim 2,

wherein the filling of the conductive paste into the through-hole by using the squeezing operation comprises:

filling the conductive paste into the through-hole by reciprocating the squeegee on the circuit board; and

the cleaning of the squeegee includes cleaning an edge of the squeegee by using the squeegee cleaning part.